

### **REMARKS**

Claims 1-16 are pending in the above-identified application. Claims 1-16 were rejected. Claims 1, 6, 10, and 13 were amended. Accordingly, claims 1-20 are at issue in the above-identified application.

### **35 U.S.C. § 103 Obviousness Rejection of Claims**

Claims 1-16 were rejected under 35 U.S.C. § 103(a) as being unpatentable over *Ota et al.* (JP 2002-163624). Applicants respectfully traverse this rejection. Withdrawal of this rejection is respectfully requested.

Claim 1 recites an IC card comprising an IC module which comprises an IC chip mounted on an insulating substrate having an antenna coil, and a chip reinforcing plate provided on at least an IC mounted surface of said insulating substrate, and a core layer comprising a plurality of sheet materials having said IC module disposed therebetween, wherein, in said plurality of sheet materials, at least the sheet materials adjacent to said IC module have a through hole for containing therein said IC chip, formed in a region corresponding to an IC mounted portion of said IC module, *wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module*, wherein a relationship  $A = (B1 + C1) \pm 30 \mu\text{m}$  is satisfied, where A ( $\mu\text{m}$ ) represents the sum of heights of said through holes, B1 ( $\mu\text{m}$ ) represents a projection height on an IC mounted surface of said IC module, and C1 ( $\mu\text{m}$ ) represents a projection height on an IC non-mounted surface of said IC module.

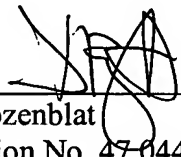
None of the prior art teaches or discloses an IC card which comprises an IC module and a core layer comprising a plurality of sheet materials, *wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC*

*module*. For example, *Ota et al.* teaches an IC card provided with an IC module enforcing 9 and 9' through sealed resins 7 and 7' on an IC chip 5 packaged on an insulated substrate 1 and on a non-packaging plane of the IC chip 5 on an insulated substrate. *Ota et al.* does not teach, however, *a core layer comprising a plurality of sheet materials wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module*. For these reasons and above, Applicants respectfully request withdrawal of this rejection.

In view of the foregoing, Applicants submit that the application is in condition for allowance. Notice to that effect is requested.

Respectfully submitted,

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